

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: L0110-04 Product Affected: PA48 & PA56 of all Logic de			DATE: 10/19/01 6 (TSSOP) packages evices		MEANS OF DISTINGUISHING CHANGED DEVICES:  Product Mark  Back Mark  Date Code		GED DEVICES:		
Date Effective: October 19, 2001					Other				
Contact:	Bimla Pau	1							
Title:	Q.A. Mana			Attachment::		Yes	☐ No		
Phone #:	(408) 654-	6419							
Fax #:	(408) 492-8362				Samples:	N/A			
E-mail:	bimla.paul@idt.com								
☐ Die Techn ☐ Wafer Fab ☐ Assembly ☐ Equipment ☐ Material ☐ Testing ☐ Manufactu ☐ Data Sheet ☐ Other  RELIABILI Moisture sensi  CUSTOMER IDT records to grant approit will be assu IDT reserves	ology rication Pro Process t  rring Site t  FY/QUALI itivity level  R ACKNOV indicate that oval or required that the right to	IFICATION S is changed from WLEDGMEN t you require watest additional in the change is according to the	To comply with the re IPC/JEDEC J-STD-0: devices will be chang (Moisture Sensitive)  Moisture sensitivity la effective 10/19/2001 effective 10/19/2001 effective 1 to level 3.  TOF RECEIPT: critten notification of the information. If IDT doctorptable.	20A. ged fr abel j (See	Moisture sense om level 1 (No per IPC/JEDE0 attachment # 1 per IPC/JEDE0 a	sivitiy levon-Moistu	el of all TSSOP 43 re Sensitive) to lev 033 will be applied cnowledgement be nent within 30 days	8 & 56 Logic vel 3  d to the dry pack.  low or E-Mail s of this notice	
				П		1 C 1 ·		CC 4: 1 4	
Customer:				Ш	Approva	i for shi	pments prior to	effective date.	
Name/Date:				E-M	Iail Address:				
Title:				Pho	one#/Fax#:				
CUSTOMER	R COMME	NTS:							
IDT ACKNO	OWLEDGN	MENT OF RE	CEIPT:						
					DATE.				
KECD. BY:				_	DATE:				

Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

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**ATTACHMENT # 1 - PCN #: L0110-04** 

## Moisture Sensitivity Label for level 3

CAUTION This Bag Contains MOISTURE- SENSITIVE DEVICES	
If Blank, see adjacen bar code label	nt
<ol> <li>Calculated shelf life in sealed bag: 12 months at &lt; 40°C and &lt; 90 relative humidity (RH)</li> </ol>	%
2. Peak package body temperature: ☐ 225° C ☐ 240° C	
<ul> <li>3. After bag is opened, devices that will be subjected to reflow sold or other high temperature process must</li> <li>a) Mounted within 168 hours of factory conditions ≤ 30° C/60%</li> <li>b) Stored at ≤10% RH</li> </ul>	ler
<ul> <li>4. Devices require bake, before mounting, if:</li> <li>a) Humidity Indicator Card is &gt;10% when read at 23 ± 5° C,</li> <li>b) 3a or 3b is not met.</li> </ul>	
5. If baking is required, devices may be baked for 48 hours at 125 ± 5°	c
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired,	
reference IPC/JEDEC J-STD-033 for bake procedure	İ
Bag Seal Date:	
If Blank, see adjacent bar code label  Note: Level and body temperature defined by IPC/JEDEC J-STD-020	)